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Part Number:	**0740401343**
Status:	**Active**
Overview:	VHDM Backplane Connector Systems
Description:	VHDM Daughtercard, 2.00mm Pitch, 8-Rows, 25 Wafers, 200 Circuits, Tin Lead, Guide Module

Documents:

Drawing (PDF)
Product Specification PS-74031-999-001 (PDF)
Packaging Specification PK-70873-5041-001 (PDF)
RoHS Certificate of Compliance (PDF)

Agency Certification

UL	E29179

General

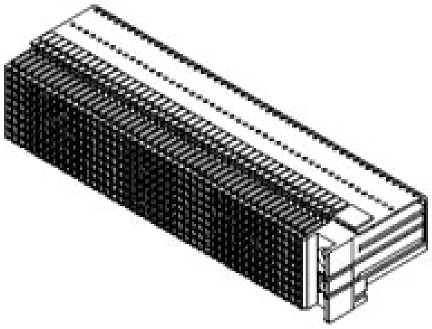
Product Family	Backplane Connectors
Series	74040
Application	Backplane
Application Tooling Documents	TM-622010999
Comments	Daughter Card
Component Type	PCB Header
Overview	VHDM Backplane Connector Systems
Product Name	VHDM
UPC	883906551841

Physical

Circuits (Loaded)	200
Circuits (maximum)	200
Color - Resin	Black
Durability (mating cycles max)	200
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	Yes
Keying to Mating Part	N/A
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Matte Tin
Material - Resin	High Performance Thermoplastic
Net Weight	59.065/g
Number of Columns	25
Number of Pairs	N/A
Number of Rows	8
Orientation	Right Angle
PC Tail Length	2.80mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.80mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Plating min - Mating	0.762µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55° to +80°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1.0A



Series image - Reference only

EU ELV
Not Relevant

EU RoHS **China RoHS**
Compliant
REACH SVHC
Not Contained Per - D(2020)4578-DC (25 June 2020)
Halogen-Free Status
Low-Halogen
For more information, please visit Contact US

China ROHS	Green Image
ELV	Not Relevant
RoHS Phthalates	Not Contained

Search Parts in this Series
74040 Series

Application Tooling | **FAQ**
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.
Global

Description	Product #
Single Wafer Removal Tool	621004300
Card Stiffener Removal Tool	622016200
Insertion Module	622020214

Data Rate	3.125 Gbps
Shielded	Yes
Voltage - Maximum	120V AC (RMS)/DC

Solder Process Data

Lead-freeProcess Capability	N/A

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-5041-001
Product Specification	PS-74031-999-001
Sales Drawing	SD-74040-1343-001

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